

# Stellant

## Electronic Component Procurement Requirement Codes

Code	Description
EC01	<b>Acceptance Test Results - Attributes Data.</b> Seller shall include with each shipment a copy of the lot or item acceptance tests summary required by the applicable specification. The report shall include the principal specifications, including revision numbers or letters, which govern the production of the item. Test reports shall include the control identity (e.g. lot, heat lot, serial number) of the material or item tested. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's test report as described above.
EC02	<b>Acceptance Test Results - Variables Data.</b> Seller shall include with each shipment a copy of the lot or item acceptance tests required by the applicable specification. The report shall include the principal specifications, including revision numbers or letters, which govern the production of the item. Where quantitative limits are established by the specification, the report shall indicate the actual values obtained during testing. Test reports shall include the control identity (e.g. lot, heat lot, serial number) of the material or item tested. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's test report as described above.
EC03	<b>X-Ray Data.</b> Seller shall include with each shipment x-ray film copies or real-time x-ray images. The report shall include the principal specifications, including revision numbers or letters, which govern the production of the item. Test reports shall include the control identity (e.g. lot, heat lot, serial number) of the material or item tested. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's documentation as described above.
EC04	<b>Group A Quality Conformance Inspection Data.</b> Seller shall include with each shipment a copy of the results of the lot or item Group A acceptance tests as required by the applicable device specification. Where quantitative limits are established by the specification, the report shall indicate the actual values obtained during testing. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's test report as described above.
EC05	<b>Group B/LAT (Lot Acceptance Test) Quality Conformance Inspection Data.</b> Seller shall include with each shipment a copy of the results of the lot or item Group B acceptance tests as required by the applicable device specification. Where quantitative limits are established by the specification, the report shall indicate the actual values obtained during testing. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's test report as described above.
EC06	<b>Group C Quality Conformance Inspection Data.</b> Seller shall include with each shipment a copy of the results of the lot or item Group C acceptance tests as required by the applicable device specification. Where quantitative limits are established by the specification, the report shall indicate the actual values obtained during testing. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's test report as described above.
EC07	<b>Group D Quality Conformance Inspection Data.</b> Seller shall include with each shipment a copy of the results of the lot or item Group D acceptance tests as required by the applicable device specification. Where quantitative limits are established by the specification, the report shall indicate the actual values obtained during testing. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's test report as described above.
EC08	<b>DPA Samples - Device Elements.</b> Seller shall include with each shipment device element samples as required per the applicable specification for Destructive Physical Analysis. Device element samples may be shipped prior to lot acceptance testing (ex. Group B) but not prior to completion of 100% screening test requirements per the applicable specification.
EC09	<b>Hot Solder Dip.</b> Prior to shipment by the Seller, all devices shall have been subjected to the Hot Solder Dip requirements of MIL-PRF-19500 para H.4.3 and Table H-I for discrete semiconductors and MIL-PRF-38535 Appendix A, paragraphs A.3.5.6.3.2 and A.3.5.6.3.4 for microcircuits.
EC10	<b>Waffle packaging.</b> Prior to shipment by the Seller, all devices shall be loaded into appropriately sized waffle packs which will provide protection against deterioration and physical damage during shipment and also meet the ESD (Electrostatic Discharge) packaging requirements of Q404.
EC11	<b>Lot Date Code Less Than 4 Years.</b> Seller shall provide all devices with a manufacturer's Lot Date Code that is less than 4 years from date of Purchase Order.
EC12	<b>Single Lot Date Code.</b> The full quantity of each part number provided under this purchase order shall have a single lot date code. Seller will obtain the written approval of L3Harris's authorized purchasing representative prior to shipping goods that do not meet this single lot date code requirement. In the event that the L3Harris's purchasing representative provides authorization in writing to ship mixed lot date codes, the seller shall provide a copy of the L3Harris written authorization with the shipping document. When mixed lot date codes are authorized, the shipper shall list individual lot date codes and quantity. Multiple lot date codes shall not be co-mingled. In addition, the individual part containers shall be marked with the quantity and lot date code.
EC13	<b>Groups A, B and C Quality Conformance Inspection Data.</b> Seller shall include with each shipment a copy of the results of the lot or item Groups A B and C acceptance tests as required by the applicable device specification. Where quantitative limits are established by the specification, the report shall indicate the actual values obtained during testing. If Seller is not the original manufacturer, Seller shall furnish the manufacturer's test report as described above.
EC14	<b>Solderability Test.</b> Solderability test in accordance with MIL-PRF-55310 Group A Subgroup 2 is required on a 5 pc sample from each lot date code after the hot solder dip finish is applied.

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EC15	<p><b><u>Destructive Physical Analysis (DPA).</u></b> A DPA on each manufacturer device lot, identified by the procurement part number and its unique Lot Date Code (LDC) attribute, shall be completed by the Seller prior to shipment of the lot to Stellant Systems (the Buyer), unless Authorization to Ship is provided by the Buyer prior to completion of DPA.</p> <p>The DPA shall be performed in accordance with Stellant Systems Statement of Work document SWB430876. However, prior to performing DPA, Seller shall provide to the Buyer the manufacturing Source of Supply, the procurement part number, and assembly LDC information, whereby the Buyer will verify that DPA history <u>doesn't</u> exist in order to allow for the DPA to proceed. The DPA requires a 5-piece device sample randomly selected from each manufacturer device lot (of unique LDC) with the following exceptions:</p> <p>(1) B430740-001 (Hybrid microcircuit) requires a sample size of 2 devices.  (2) B430740-002 (Hybrid microcircuit) requires a sample size of 2 devices.  (3) B429541-001 (Hybrid microcircuit) requires a sample size 1 device.</p> <p>The DPA shall be performed by Hi-Rel Laboratories (HRL), 6116 N. Freya, Spokane, WA. Seller shall provide the Buyer access to HRL In-process DPA Notifications (via E-mails) and access to HRL On-line Secure Access File Exchange database to allow access and review of completed HRL DPA reports.</p> <p>Approval of each HRL DPA report is required by the Buyer to allow the Seller to ship respective manufacturer device lots.</p>
EC16	<p><b><u>Destructive Physical Analysis(DPA) performed by manufacturer approved DPA Lab.</u></b>  A DPA on each manufacturer device lot, identified by the procurement part number and its unique Lot Date Code (LDC) attribute, shall be completed by the manufacturer prior to shipment of the lot to Stellant Systems (the Buyer), unless Authorization to Ship is provided by the Buyer prior to completion of DPA.</p> <p>The DPA shall be performed in accordance with the latest revision of MIL-STD-1580.</p> <p>A 5 piece device sample randomly selected from each manufacturer device lot (of unique LDC) will be subjected to DPA. Samples shall be selected after the hot solder dip termination finish has been applied to the devices.</p> <p>The DPA shall be performed at a test lab deemed acceptable by EPC Space. If DPA results are acceptable, the DPA report shall be included in the data package that is included with the shipment of parts to Stellant Systems. If the DPA results are not acceptable, the lot of parts shall not be shipped to Stellant, unless the issue has been discussed with Stellant and Stellant has agreed to accept the parts.</p>
EC17	<p><b><u>Hot Solder Dip Finish and Solderability Test for ISL71610SLHMBZ</u></b>  A Sn63Pb37 hot solder dip finish shall be applied by Spirit Electronics via robotic process to all devices in a lot from the shoulder of the lead to the foot of the lead, in accordance with router SOS3823VX.</p> <p>Subsequent to the hot solder dip process, a solderability test in accordance with MIL-STD-883 Method 2003 will be performed on a 3 piece sample for each lot of devices(identified by 6 digit code, YYWWXX, assigned by Intersil/Renesas). A traveler for the hot solder dip process and solderability test results will be shipped to Stellant with each lot of parts.</p>
EC18	<p><b><u>Screening and QCI Testing of FBG20N18BSH</u></b>  FBG20N18BSH transistors shall be subjected to the screening, Group A, Group B, Group C and Group D quality conformance inspection and performance requirements in accordance with EPC Space drawing 70-024 which is a Stellant specific version of SCD-20N18B-001-C. Group E is only required if the part requires requalification.</p>